

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3439641

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
EUN DONG KIM	07/10/2015
JONG WON LEE	07/10/2015
JAI KYOUNG CHOI	07/14/2015
RECEIVING PARTY DATA	
Name:	STS SEMICONDUCTOR & TELECOMMUNICATIONS CO., LTD.
Street Address:	16, BAEKSEOKGONGDAN 7-RO, SEOBUK-GU, CHEONAN-SI
City:	CHUNGHEONGNAM-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	136-729
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14799875
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ATTORNEY DOCKET NUMBER:	35008-00003
NAME OF SUBMITTER:	SUNWOO LEE
SIGNATURE:	/Sunwoo Lee/
DATE SIGNED:	07/15/2015
Total Attachments: 2	
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source=35008_00003_Assignment#page2.tif	

ASSIGNMENT

WHEREAS I, the below named inventor, [hereinafter referred to as Assignor], has made an invention entitled:

METHOD OF MANUFACTURING WAFER LEVEL PACKAGE

for which we executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Application No. _____); and

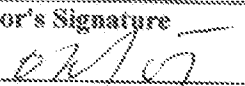
WHEREAS, STS Semiconductor & Telecommunications Co., Ltd. a corporation of the Republic of Korea whose post office address is 16, Backseokgongdan 7-ro, Seobuk-gu, Cheonan-si, Chungcheongnam-do, 330-220 Republic of Korea (hereinafter referred to as Assignees), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignees is hereby acknowledged, I, as assignor, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignees, its lawful successors and assigns, our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and we hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

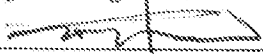
AND, I HEREBY further covenant and agree that I will, without further consideration, communicate with assignees, its successors and assigns, any facts known to us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignees, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignees, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignees, its successors and assigns.

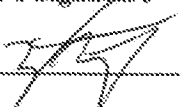
AND, I HEREBY authorize and request the attorneys we have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

Full Name of Assignor Eun Dong KIM	Assignor's Signature 	Date July 10 '15
Address: # 206-501, 35, Jongam-ro 23-gil, Seongbuk-gu, Seoul, 136-729, Republic of Korea		Citizenship KR

Names of additional inventors attached ☒ Yes ☐ No

Full Name of Assignor Jong Won LEE	Assignor's Signature 	Date 2015. 7. 10
Address: #1-401, Yangwonmyeok-ro, Jungnang-gu, Seoul, 131-800, Republic of Korea		Citizenship KR

Full Name of Assignor Jai Kyoung CHOI	Assignor's Signature 	Date 2015. 7. 14
Address: #101-1905, 9, Annam-ro, Dongnae-gu, Busan, 607-756, Republic of Korea		Citizenship KR

Names of additional inventors attached ☐ Yes ☒ No